

**MAG-4.2-T011-D002**  
**Test of R&W Prototype Joint**

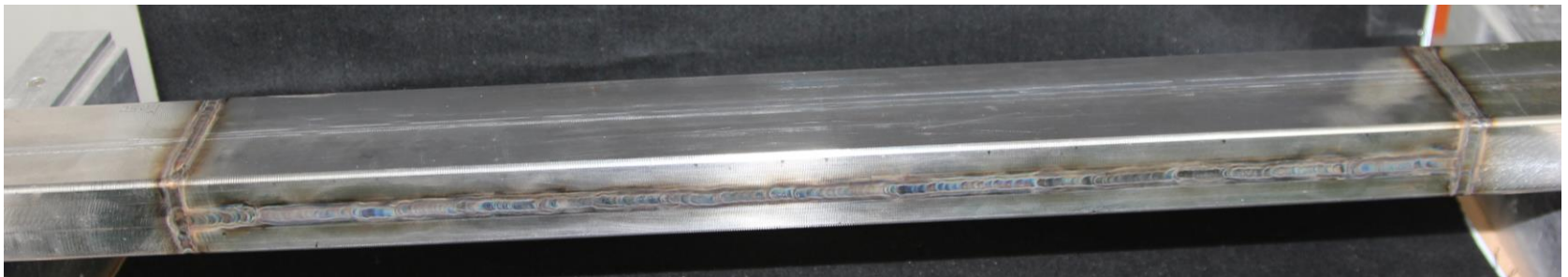
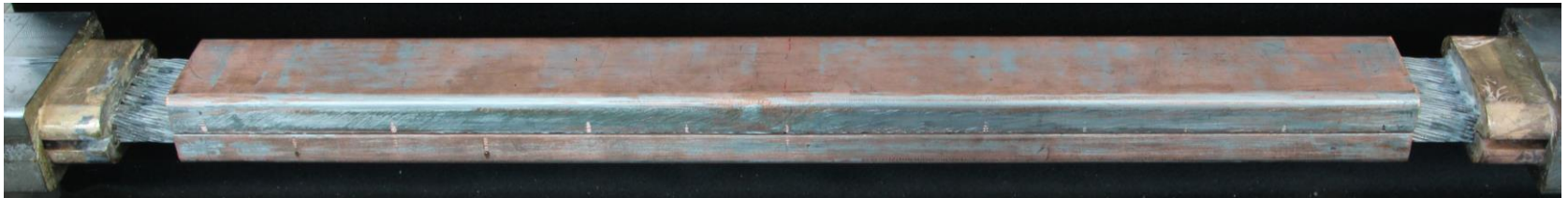
WPMAG Final Meeting 2019

V. D'Auria, B. Stepanov, K. Sedlak, P. Bruzzone

- Background of RW2 joint
- RW2 joint using diffusion-bonding technique (RW2J2)
  - Assembly
    - Cables preparation before bonding
    - Diffusion bonding
    - SULTAN sample
  - Test results
    - Electrical resistance
    - AC losses  $\perp$  and  $\parallel$  to the broad side
  - Conclusions and perspectives

# Background of RW2 Joint

- In 2017 failed test of a butt-joint with superconducting bridges (RW2J1). Resistance 3-13 n $\Omega$  at 0-11 T

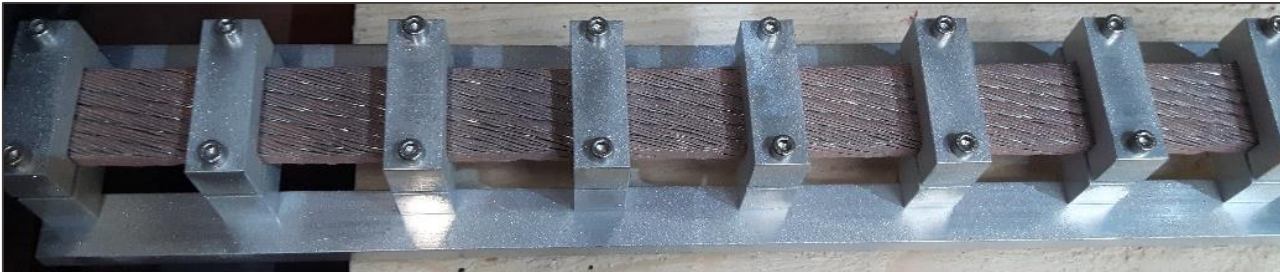


- Inter-layer joint for **React&Wind** cables → joint during winding
- **Overlap geometry**



- Target  $R \leq 1 \text{ n}\Omega$  at operating conditions,  $B=8 \text{ T}$  and  $I=63.3 \text{ kA}$
- **Diffusion bonding joint** (N.B. cables already heat treated) → no solder, no flux agents, no indium wires.
- Techniques/tools compatible with **in situ assembly**, including:
  1. Copper spraying method to **flatten the surfaces**
  2. Clamp to keep **pressure**,  $\approx 30 \text{ MPa}$
  3. Oven to keep **temperature**,  $\approx 650 \text{ }^\circ\text{C}$

- Background of RW2 joint
- RW2 joint using diffusion-bonding technique (RW2J2)
  - Assembly
    - Cables preparation before bonding
    - Diffusion bonding
    - SULTAN sample
  - Test results
    - Electrical resistance
    - AC losses  $\perp$  and  $\parallel$  to the broad side
  - Conclusions and perspectives



- Aluminum clamps & bars as support



- Sandblasting & copper-spray in multistage



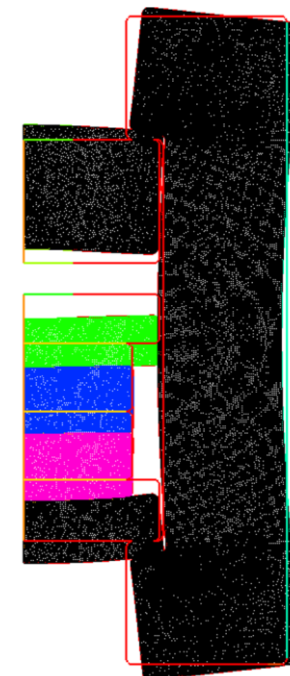
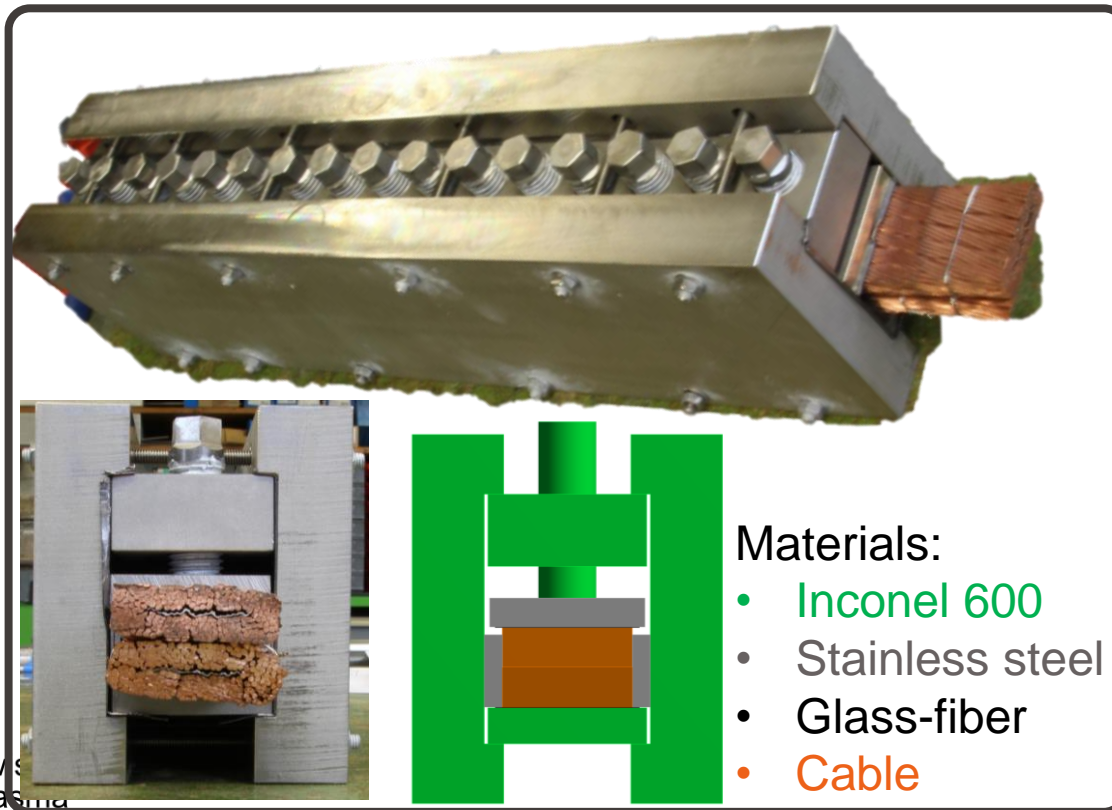
- Surfaces milled flat



- Background of RW2 joint
- RW2 joint using diffusion-bonding technique (RW2J2)
  - Assembly
    - Cables preparation before bonding
    - Diffusion bonding
    - SULTAN sample
  - Test results
    - Electrical resistance
    - AC losses  $\perp$  and  $\parallel$  to the broad side
  - Conclusions and perspectives

# EPFL RW2J2 – 2. Clamp

- Target joint pressure @ 650 °C is 30 MPa
- Clamp design criteria:
  - Disassembly after diffusion-bonding
  - Joint pressure homogeneity
  - Choice of materials such that  $p=24 \text{ MPa} @ 20 \text{ °C} \rightarrow p=30 \text{ MPa} @ 650 \text{ °C}$



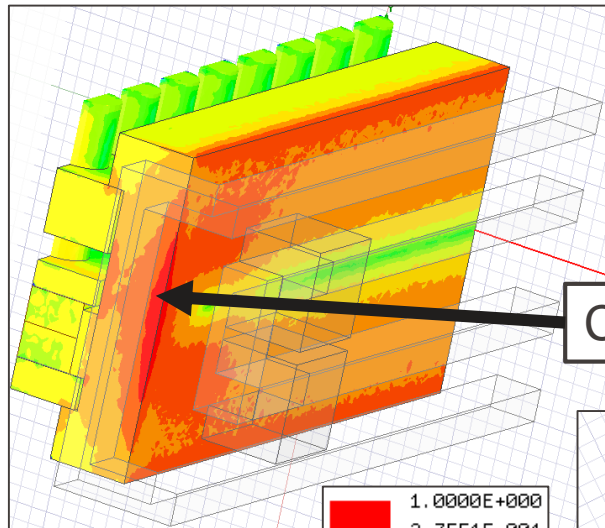
Displacement amplification factor=50



# RW2J2 – 3. Oven to keep temperature (I)

- Portable inductive copper oven
- Inductors optimized  $\rightarrow$  cable temperature as homogeneous as possible

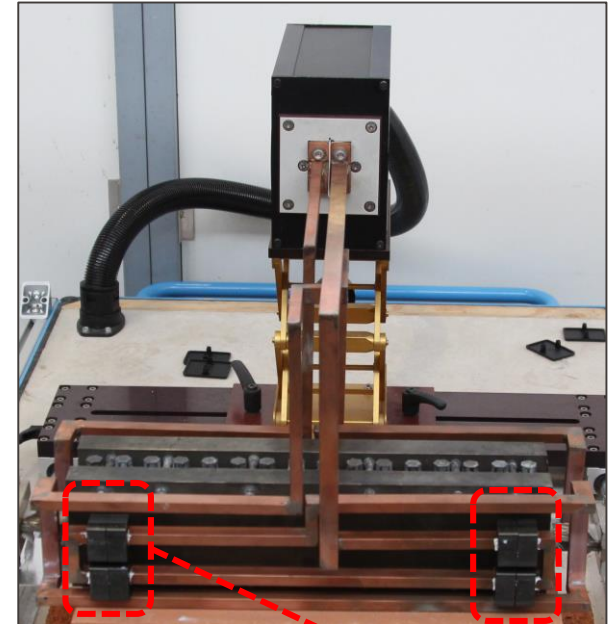
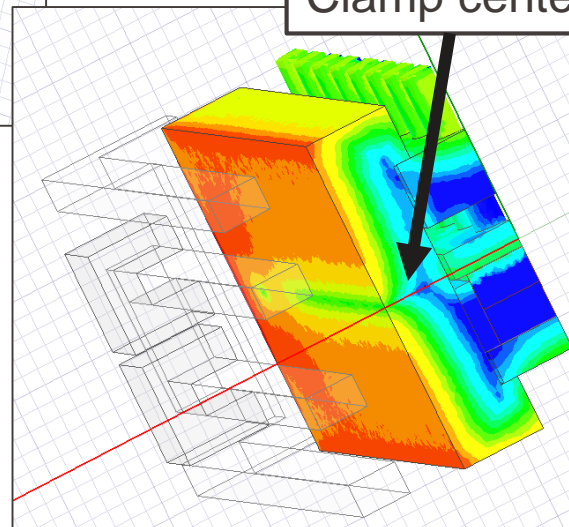
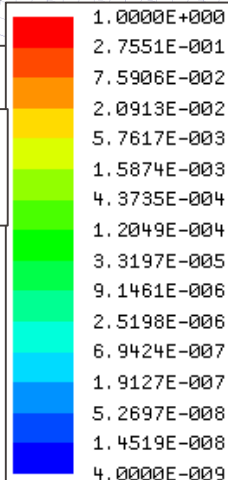
- $f=52.3 \text{ kHz}$
- $P=4.6 \text{ kW}$



Clamp end

Clamp center

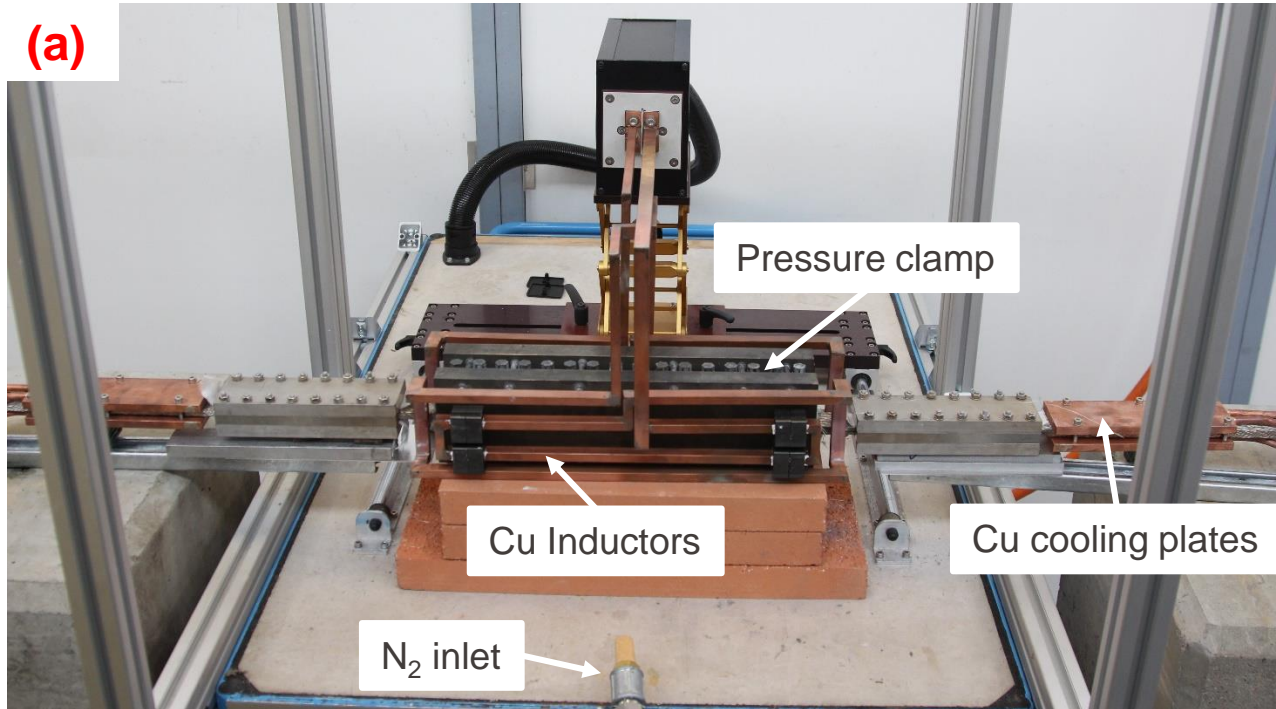
Normalized  
Ohmic Losses



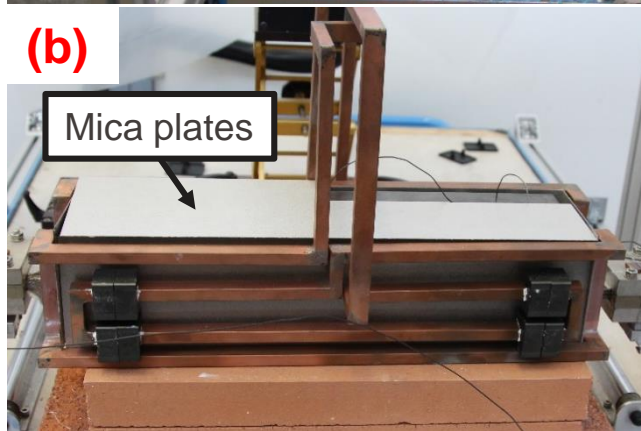
*Ferrite blocks  
focus field lines*



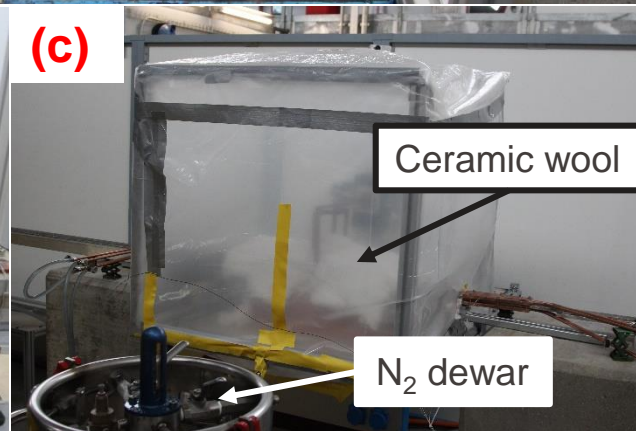
(a)



(b)



(c)



a) Oven and cable ends active cooling

b) Mica plates shield from thermal radiation.

c) Inert atmosphere with  $N_2$

■ Cable T @ steady-state ( $P=4.6\text{ kW}$ ,  $f=52.3\text{ kHz}$ ):

- $690\text{ }^\circ\text{C}$  @ cable center
- $620\text{ }^\circ\text{C}$  @ cable ends
- $20\text{ }^\circ\text{C}$  @ Cu plates

■ Times:

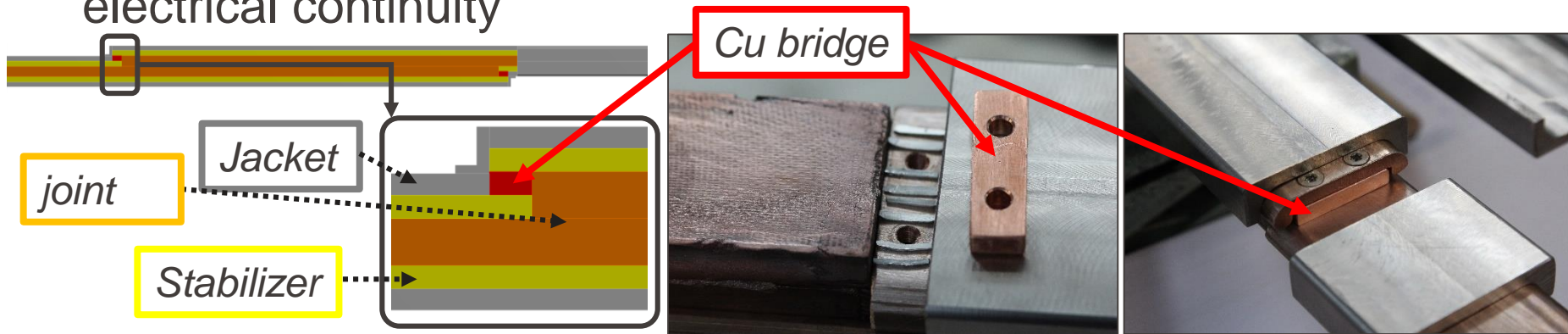
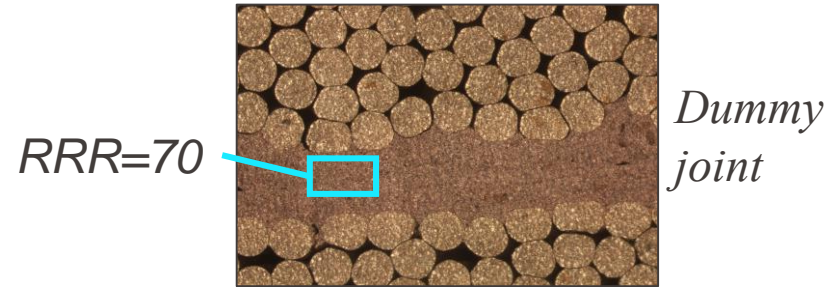
- 1.5 h to get steady-state
- 2 h of diffusion-bonding
- 6 h cool-down

$$f=52.3\text{ kHz}, P=4.6\text{ kW}$$

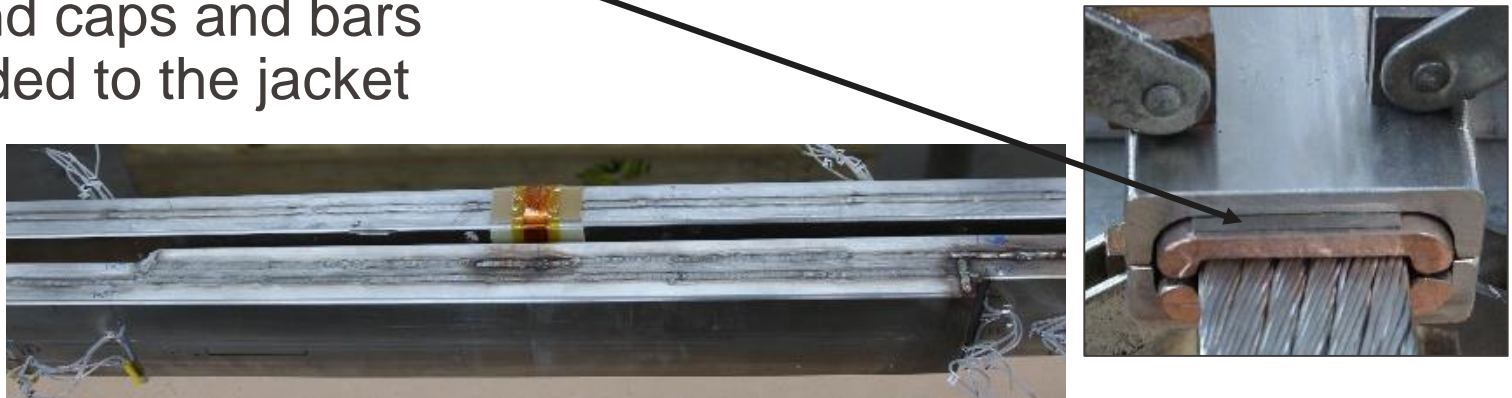
- Background of RW2 joint
- RW2 joint using diffusion-bonding technique (RW2J2)
  - Assembly
    - Cables preparation before bonding
    - Diffusion bonding
    - SULTAN sample
  - Test results
    - Electrical resistance
    - AC losses  $\perp$  and  $\parallel$  to the broad side
  - Conclusions and perspectives

# EPFL RW2J2 – SULTAN sample

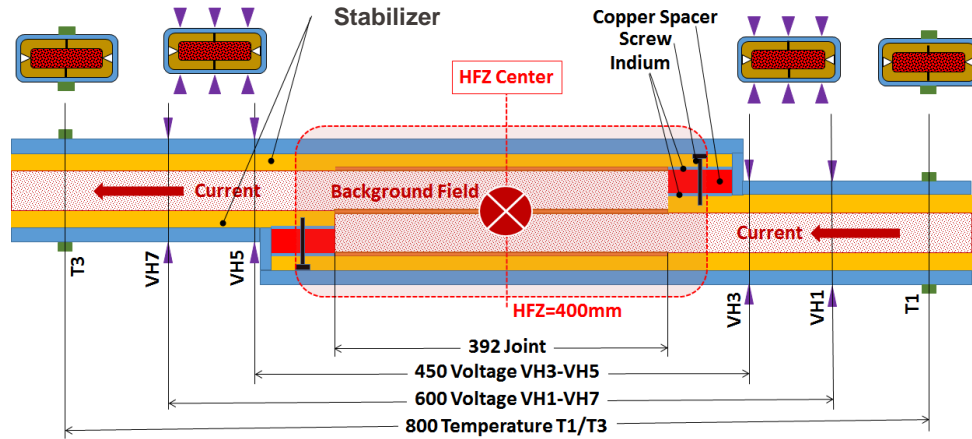
- Stabilizer is machined according to joint dimensions
- Copper bridge with indium ensures full matrix stabilizer electrical continuity



- Cable preload with thin steel foil between jacket and stabilizer
- Steel end caps and bars are welded to the jacket

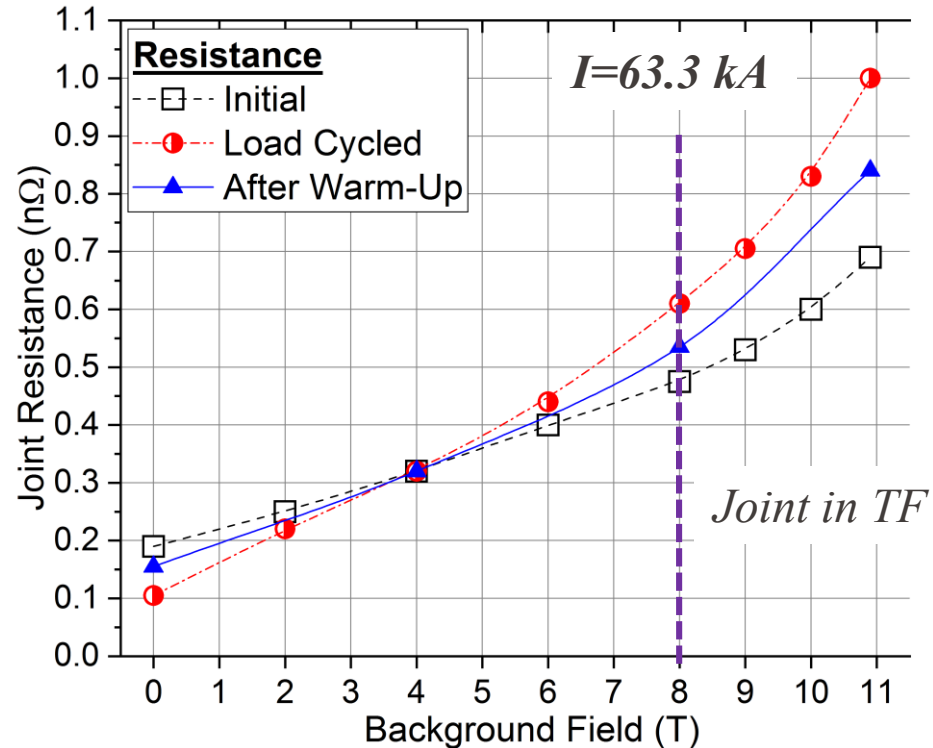


- Background of RW2 joint
- RW2 joint using diffusion-bonding technique (RW2J2)
  - Assembly
    - Cables preparation before bonding
    - Diffusion bonding
    - SULTAN sample
  - Test results
    - Electrical resistance
    - AC losses  $\perp$  and  $\parallel$  to the broad side
  - Conclusions and perspectives



- V-taps arrays at 450 mm and 600 mm.  $R$  @ different  $I$ -flat-top and  $B$

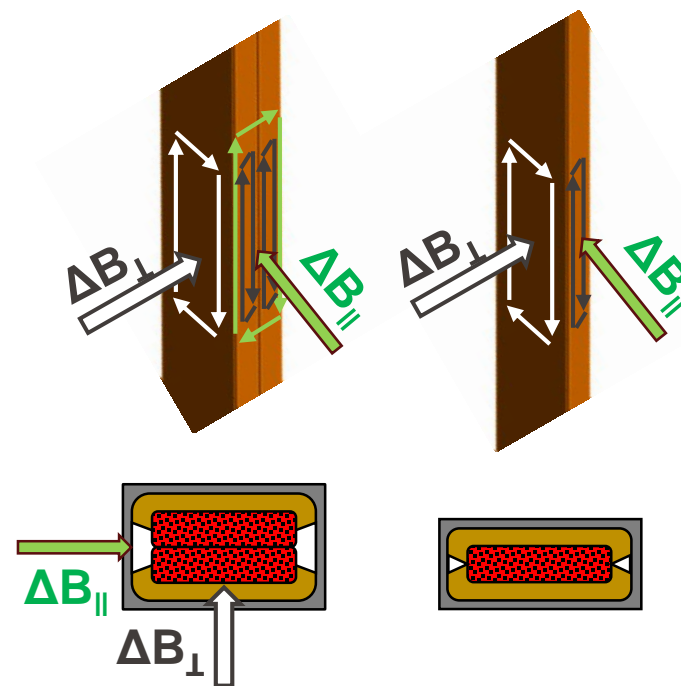
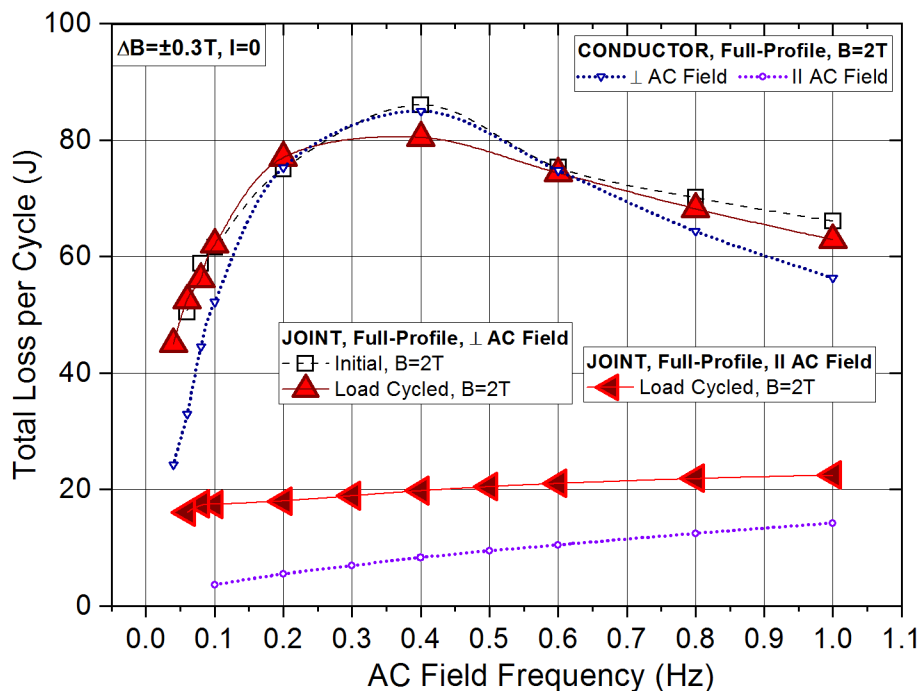
- $R(B)$  behavior according to **Cu magneto-resistance** for the “initial” curve
- Higher difference between  $R_{450mm}$  and  $R_{600mm}$  after cycling (8Tx63.3kA=506 kN/m). We suspect **damage @ joint sides**



- Background of RW2 joint
- RW2 joint using diffusion-bonding technique (RW2J2)
  - Assembly
    - Cables preparation before bonding
    - Diffusion bonding
    - SULTAN sample
  - Test results
    - Electrical resistance
    - AC losses  $\perp$  and  $\parallel$  to the broad side
  - Conclusions and perspectives

# EPFL Test results – AC losses and Transient Stability Test

- Comparison between joint and conductor at  $B=2 \pm 0.3$  T sinusoidal pulse
- AC field  $\perp$  broad face
  - No screening @ lower  $f \rightarrow$  joint AC losses  $\approx$  twice as conductor ones
  - Screening @ higher  $f \rightarrow$  joint and conductor losses are similar
- AC field  $\parallel$  broad face: new current loops make comparison with conductor not scalable
- Transient stability test at  $B=8$  T,  $I=63.3$  kA  $\rightarrow$  quench in conductor leg if  $dB/dt > 17.6$  T/s in 128 ms. Deposited energy in joint **65 J**





- MAG-4.2-T011-D002 completed
- We have a joint reference for layer-wound DEMO RW magnets

## Further R&D

- Further characterization of the joint
  - Mechanical tests with KIT (TS for KIT)
  - Micrographs to study joint uniformity
- The mechanical design of the joint (jacket, stabilizer, fillers) can be improved
- A new joint may be prepared using RW3 late next year



- Measuring RRR sprayed copper



▪ Diffusion bonding temperature distribution

